

## **REMARKS/ARGUMENTS**

### ***Status of the Application***

In the March 28, 2006, Non-Final Office Action, Claims 1-11 were rejected. In the present response, step c) of Claim 1 was amended to clarify that a coated electrical steel sheets obtained in step b) is assembled with at least one additional electrical steel sheet to form a sheet core (see page 5, line 27 – page 6, line 5 for support). Claim 2 was amended to clarify that “adding dicyandiamide and the further components” means adding components B) – E) (support comes from Claim 2 itself, as well as Claim 1). Claim 4 was amended to clarify that the “finished composition” is the composition of step a) (see Claim 1 for support).

Thus, Claims 1-11 are pending. No new matter was added.

### ***Rejections Under 35 U.S.C. § 112, 2<sup>nd</sup> Paragraph***

Claims 1-11 were rejected under 35 U.S.C. § 112, 2<sup>nd</sup> Paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. Applicants respectfully submit that the amendments to Claims 1, 2, and 4 overcome said rejections.

### ***Rejections Under 35 U.S.C. § 103(a)***

Claims 1-7 and 9-11 were rejected under 35 U.S.C. § 103(a) as being unpatentable over JP 11-162723 in view of JP 2000-34574 and optionally in view of Young (U.S. Patent No. 5,500,462). Applicants respectfully traverse these rejections.

JP 11-162723 discloses the use of a bisphenol A type epoxy resin and a hardening agent. The JP 11-162723 specification notes that the “elevated temperature bond strength improves further by carrying out the compound addition of phenol resin and the latency curing agent as a curing agent” (see page 3, paragraph 0014, of the computer translation attached herewith). This elevated-temperature bond strength is the goal of JP 11-162723, as mentioned at page 3, paragraph 0013 (“outstanding bond strength under ordinary temperature and hot environments”). This property is characterized by some curing agents (at least being phenol resin, and by the loadings of the latency curing agent (which can be dicyandiamide) to the phenol resin (see page 3, paragraph 0016). Consequently,

Applicants respectfully submit that JP 11-162723 teaches the use of phenol resin and the latency curing agent, which act together as the curing agent for the bisphenol A type epoxy resin.

Applicants' claimed invention, however, covers the use of dicyandiamide without any phenol resin as further curing agent. Applicants' claimed invention is instead based on another curing mechanism: the polyaddition reaction between the epoxy resin and dicyandiamide. JP 11-162723, on the other hand, is based on a curing mechanism characterized by a polycondensation reaction between the epoxy resin and the phenol resin and a polyaddition reaction (see page 5, paragraphs 0027-0028). Applicants' claimed invention does not need the additional phenol resin as curing agent, and consequently a polycondensation reaction, to provide the desired properties.

In regards to flow agent D) of Claim 1, JP 11-162723 does not disclose the meaning of the terms "membrane formation assistant" or "dispersibility improver" and does not provide examples of their use. Flow agent D), however, increases the film formation during the curing process at a higher temperature; it is not an agent to increase dispersing properties nor does it influence membrane properties. Thus, Applicants fail to see how JP 11-162723 teaches that a membrane formation assistant or a dispersibility improver is equivalent to Applicants' flow agent as suggested by the Examiner on page 3 of the March 28, 2006, Non-Final Office Action. The citation of JP 2000-34574 as providing a suggestion for the use of the polyethylene glycol Nonion surfactant as the Claim 1 flow agent is similarly unhelpful to the alleged *prima facie* case of obviousness because the Nonion surfactant is not a flow agent as is found in Claim 1. Applicants thus respectfully submit that flow agent D) of Applicants' Claim 1 invention is not disclosed or suggested by the JP 11-162723/JP 2000-34574 combination.

Young fails to add to any disclosure or suggestion to the teachings of the JP 11-162723/JP 2000-34574 combination that renders Applicants' Claim 1 invention obvious.

Because Claims 2-7 and 9-11 are dependent claims, which recite even further limitations to the claim that has already been traversed, Applicants rely upon the arguments presented above in rebuttal to the Examiner's assertion that Claims 2-7

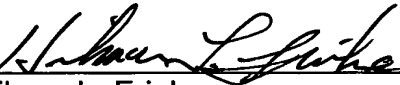
and 9-11 are unpatentable over JP 11-162723 in view of JP 2000-34574 and optionally in view of Young.

Claim 8 was rejected under 35 U.S.C. § 103(a) as being unpatentable over JP 11-162723 in view of JP 2000-34574 and optionally in view of Young further in view of Stark (U.S. Patent No. 4,307,212) or Kohn *et al.* (U.S. Patent No. 2,962,410). Because claim 8 is a dependent claim, which recites even further limitations to the claim that has already been traversed, Applicants rely upon the arguments presented above in rebuttal to the Examiner's assertion that Claim 8 is unpatentable over the above-cited references.


### Summary

In view of the foregoing amendments and remarks, Applicants submit that this application is now in condition for allowance. In order to expedite disposition of this case, the Examiner is invited to contact either of Applicants' representatives at the telephone numbers listed below to resolve any remaining issues. Should there be any additional fee due which is not accounted for, please charge such fee to Deposit Account No. 04-1928 (E.I. du Pont de Nemours and Company).

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